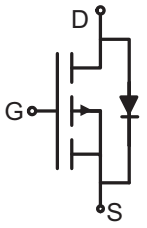
RECTRON SEMICONDUCTOR
TECHNICAL SPECIFICATION

RM50P40LD

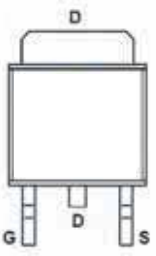
P-Channel Enhancement Mode Power MOSFET

Description

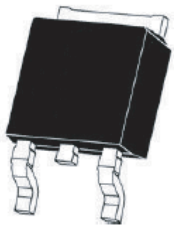
The RM50P40LD uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.



Schematic diagram



Marking and pin assignment



TO-252-2L top view

General Features

- V_{DS} =-40V,I_D =-52A
  $R_{DS(ON)}$ <13mΩ @V_{GS}=-10V
  $R_{DS(ON)}$ <20mΩ @V_{GS}=-4.5V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Load switching
- Hard switched and high frequency circuits
- Uninterruptible power supply
- Halogen-free

100% UIS TESTED!
100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Package	Packaging Code	Reel Size	Quantity(Pcs)	Carton(Pcs)
50P40	RM50P40LD	TO-252-2L	-W	13inch	2500	20000

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-40	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous	I_D	-52	A
Drain Current-Continuous(T_C=100℃)	I_D (100℃)	-32	A
Pulsed Drain Current	I_{DM}	-105	A
Maximum Power Dissipation	P_D	52.1	W
Single pulse avalanche energy (Note 5)	E_{AS}	146	mJ
Operating Junction and Storage Temperature Range	T_J,T_{STG}	-55 To 150	℃

Thermal Characteristic

Thermal Resistance,Junction-to-Case (Note 2)	$R_{\theta JC}$	2.4	℃/W

Electrical Characteristics (T_C=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D= -250μA	-40	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=-32V,V_{GS}=0V	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=-250μA	-1.0	-1.6	-2.5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=-10V, I_D=-18A	-	10.5	13	mΩ
		V_{GS}=-4.5V, I_D=-12A	-	15	20	mΩ
Forward Transconductance	g_{FS}	V_{DS}=-5V, I_D=-18A	-	24	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C_{lss}	V_{DS}=-15V,V_{GS}=0V, F=1.0MHz	-	3500	-	PF
Output Capacitance	C_{oss}		-	323	-	PF
Reverse Transfer Capacitance	C_{rss}		-	222	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=-15V,I_D=-1A,R_L=1Ω V_{GS}=-10V,R_G=3.3Ω	-	40	-	nS
Turn-on Rise Time	t_r		-	35.2	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	100	-	nS
Turn-Off Fall Time	t_f		-	9.6	-	nS
Total Gate Charge	Q_g	V_{DS}=-20V,I_D=-12A, V_{GS}=-4.5V	-	27.9	-	nC
Gate-Source Charge	Q_{gs}		-	7.7	-	nC
Gate-Drain Charge	Q_{gd}		-	7.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	V_{GS}=0V,I_S =-1A	-	-	-1	V
Diode Forward Current (Note 2)	I_S		-	-	-52	A

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. E_{AS} condition : Tj=25℃,V_{DD}=20V,V_G=10V,L=1mH,Rg=25Ω，

RATING AND CHARACTERISTICS CURVES (RM50P40LD)

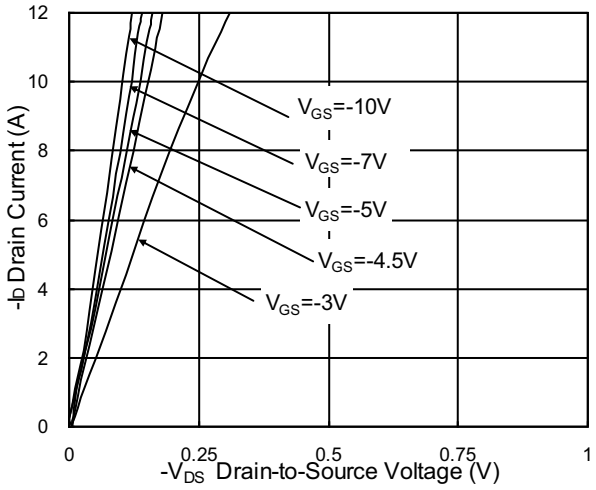


Fig.1 Typical Output Characteristics

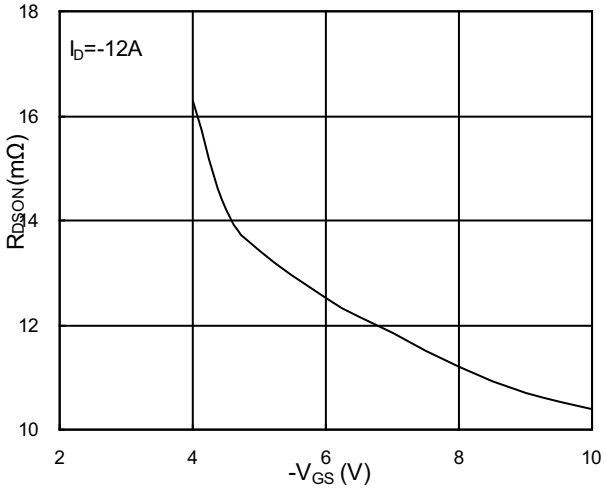


Fig.2 On-Resistance v.s Gate-Source

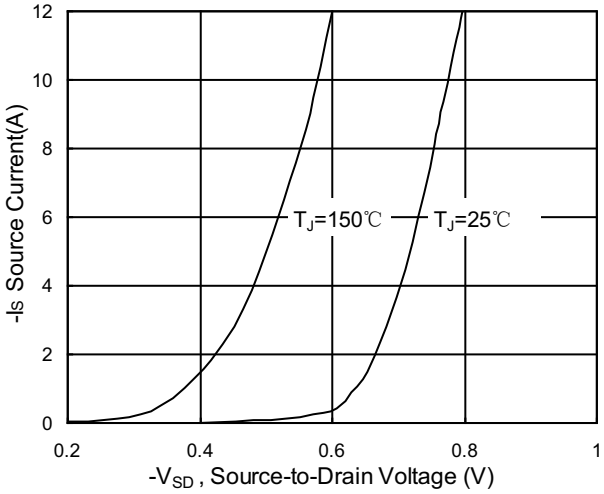


Fig.3 Forward Characteristics Of Reverse

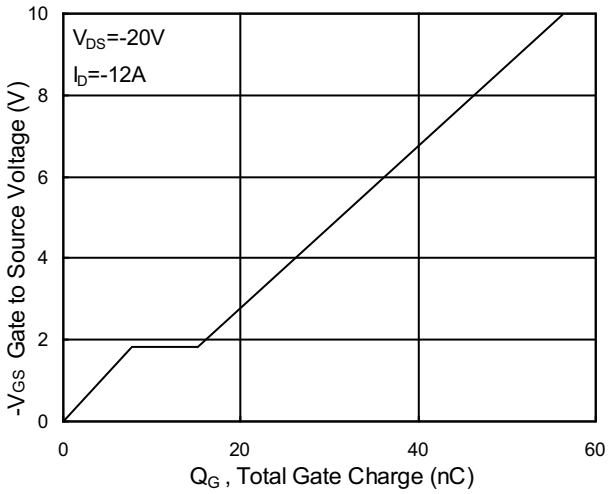


Fig.4 Gate-Charge Characteristics

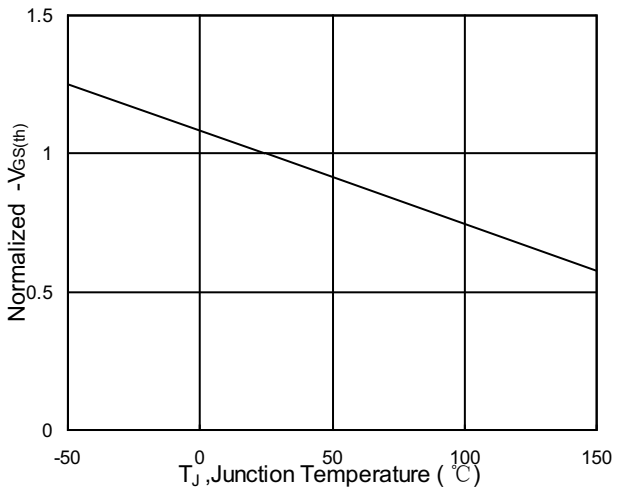


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

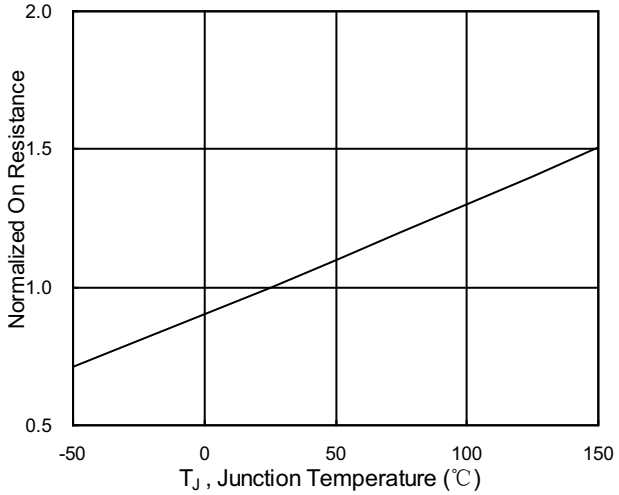


Fig.6 Normalized R_{DSON} v.s T_J

RATING AND CHARACTERISTICS CURVES (RM50P40LD)

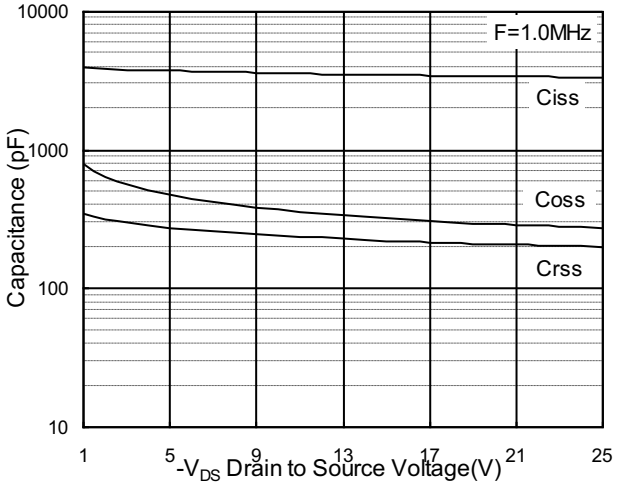


Fig.7 Capacitance

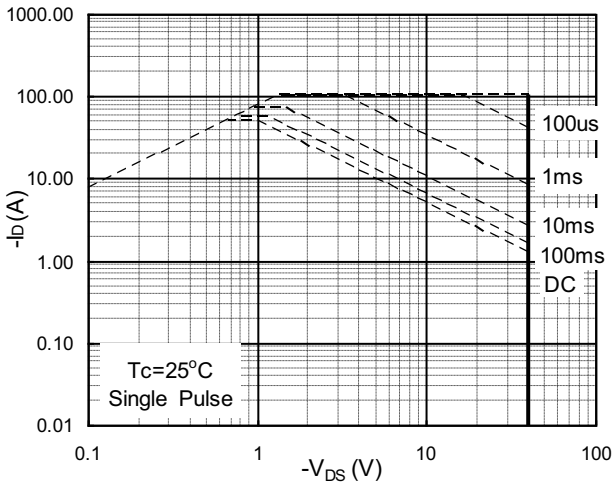


Fig.8 Safe Operating Area

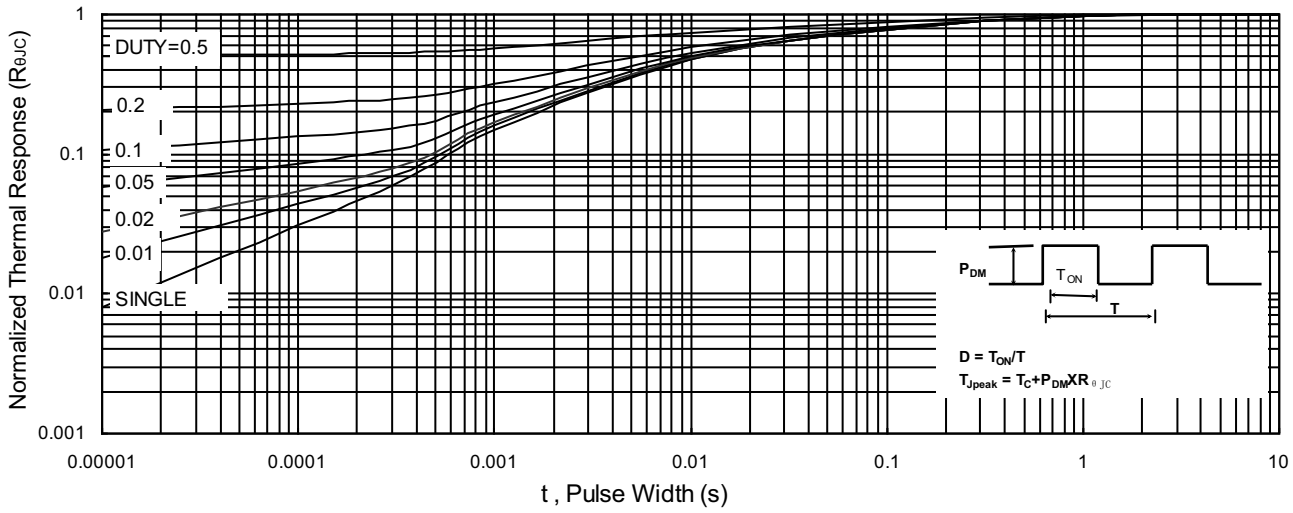


Fig.9 Normalized Maximum Transient Thermal Impedance

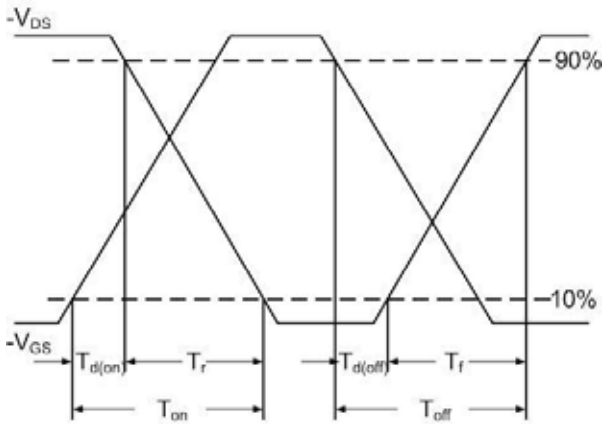


Fig.10 Switching Time Waveform

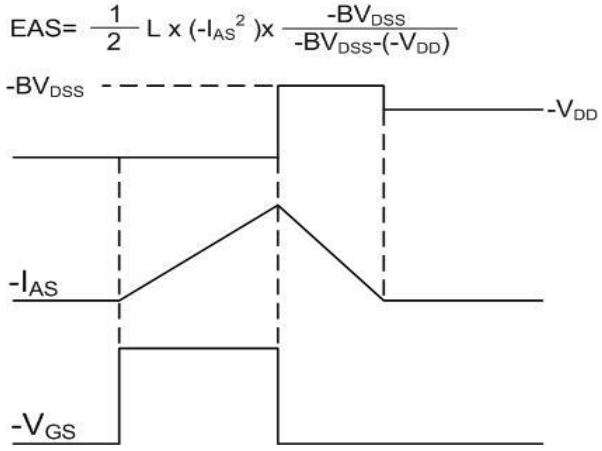
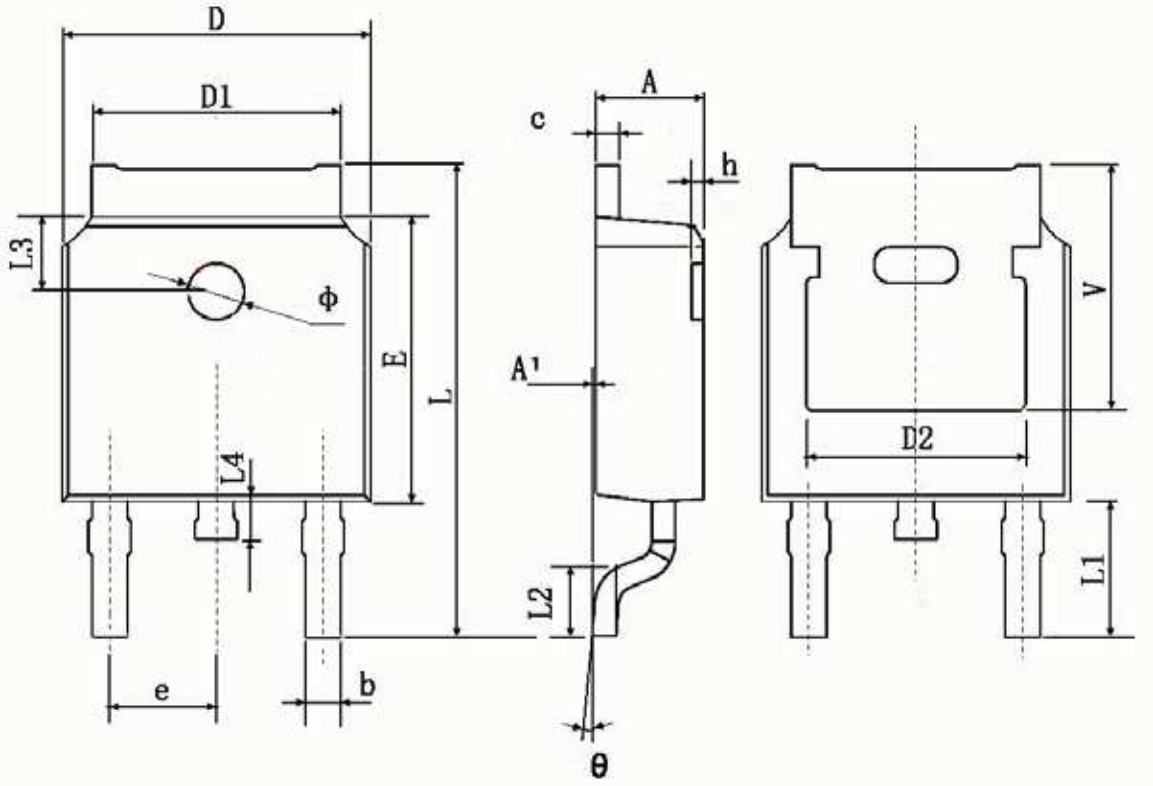


Fig.11 Unclamped Inductive Waveform

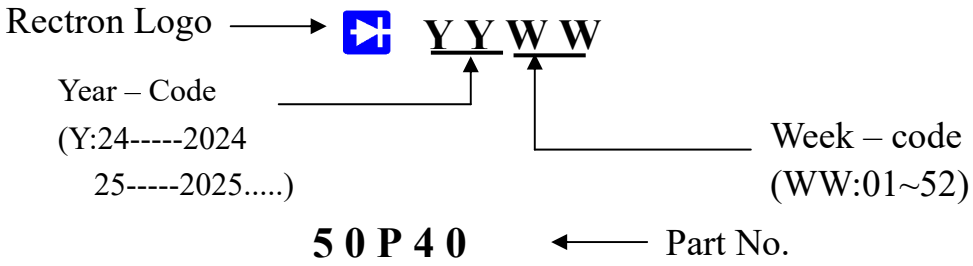
TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.700	2.000	0.067	0.079
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

RECTRON

Marking on the body



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